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# Meeting JEDEC specifications, these high-speed DDR4 DIMM sockets offer greater PCB real-estate and cost savings with excellent assembly processing compatibility

Meeting JEDEC specifications, Molex's Vertical SMT and Through hole DDR4 DIMM sockets support \*UDIMMs, RDIMMs and LRDIMM memory applications over a wide range of high-speed data, computing, telecommunication and networking servers with data speed of 3.2 billion transfers per second – twice that of DDR3 – and higher energy savings with lower 1.2V operating voltage (compared with 1.5V for DDR3).

With Molex's DDR4 DIMM sockets, more PCB real estate and cost savings can be achieved. Both series 78726 and 78730 sockets feature reduced connector footprint of 6.50mm (max.) (W) by 162mm (L) for maximum space-savings. The soldertails of the (series 78730) SMT socket are flush with the edges of the connector (that is, no protrusion of soldertails beyond the width of the connector at the base) for minimized bending damages due either to human or machine error.

Other hallmarks of Molex's DDR4 sockets include: high dimensional stability and excellent compatibility in Halogen-free and lead-free technologies. The use of moisture-resistant, high-temperature housing material – regardless of termination styles - minimizes blistering on the connector during high, IR-reflow processing temperatures. Reduced yield losses with the use of Molex DDR4 sockets add to greater customer cost savings and delivery speed.

Ergonomically designed socket latches enhance usability with robust protection against high rip-out force and vibration-resistance. Dual-side leadins on the socket facilitate smooth module insertion while stand-offs at the base of the socket makes solder-joint inspection, measurement and rework easy.

Molex offers 0.76 and 0.38 micron Gold (Au)-plated DDR4 DIMM sockets in a combination of several housing and latch colors, PC tail lengths and PCB thicknesses. All sockets are shipped in tray packaging.

For more information, visit our website at: www.molex.comlink/ddr4..html.

#### **Features and Benefits**

Reduced connector footprint of 6.50mm (max.) (W) by 162mm (L)	Provides increased PCB space and cost savings
Robust and more ergonomic latch design	Improves rip-out force and vibration resistance; makes socket easy to use
Profiled contact terminals	Eliminate stress caused to housing during terminal insertion and prevents housing warpage
Moisture-resistant, high-temperature housing material	Gives added dimensional stability to connector with reduced yield loss and increased cost-savings. Able to withstand infrared (IR), lead-free and wave soldering temperatures
High connector durability	Supports up to 25 mating cycles
Step-and-ramp feature (on connector housing and memory module)	Reduces insertion force of module without engaging all gold fingers at the same time during module insertion

### \* UDIMMs: Unbuffered DIMMs offer the fastest memory speeds, lowest latencies, and (relatively) low power consumption but are limited in capacity though.

RDIMM: Registered DIMMs, with their registers, are able to buffer the Address and Command signals between the DRAMs and the memory controller thus increasing the amount of memory that a server can support, however, with increased power consumption and memory latency.

LRDIMM: Load Reduced DIMMs use a buffer to reduce memory loading to a single load on all DDR signals, allowing for greater density but at the highest power usage

#### DDR4 DIMM Sockets, Halogen-free

**78726** Vertical, Through hole **78730** Vertical, SMT



Halogen-free DDR4 DIMM Sockets, SMT (top) and Through hole (bottom) versions



#### **Specifications**

#### **Reference Information**

Packaging: Tray UL File No.: TBA CSA File No.: TBA

Use With:

JEDEC MO-310A memory modules

Designed In: Millimeter

RoHS: Yes

Halogen Free: Yes

Glow Wire Compliant: No

#### **Electrical**

Voltage (max.): 29V AC (RMS)/DC Current (max.): 0.75A per pin Low Level Contact Resistance (max.):

10 milliohms

Dielectric Withstanding Voltage:

500V AC

Insulation Resistance (min.):

1 megohm

#### **Mechanical**

Module Insertion Force (with Latches): 12.96 kgf Module Rip-out Force (min.):

9.10 kgf

Module Unmating Force

(of 1.33mm thick blade from

socket): 2.02 kgf

Terminal Retention Force (min.):

: 0.30 kgf (contact) : 1.33 kgf (forklock) Latch Actuation Force: 4.50 kgf per latch

Durability (min.): 25 cycles

#### DDR4 DIMM Sockets, Halogen-free

#### **Physical**

Housing:

Halogen-free, high-temperature Nylon, glass-filled, UL94V-0 (both

socket and latch) Contact: Copper Alloy

Plating:

Contact Area — Refer to table below Solder Tail Area —

2.54μm (100μ") Tin (Sn)

Underplating —

1.27μm (50μ") Nickel (Ni)

PCB Thickness:

Refer to table below

(for through hole version only)

Operating Temperature:

-55 to +85°C

#### **Product Features**

#### Key differences between DDR3 and DDR4 DIMM Sockets

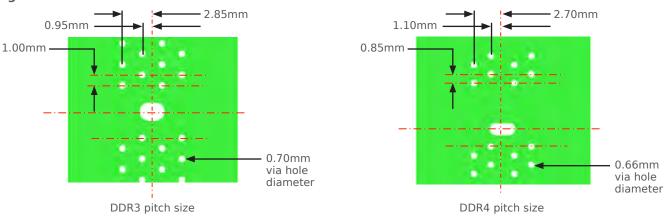
Features	DDR3 DIMM Sockets	DDR4 DIMM Sockets	
Pitch	1.00mm	0.85mm	
Module Thickness	1.27mm	1.40mm	
Circuits	240	288	
Key from Module Center	12.00mm	5.15mm	
Voltage	1.5V	1.2V	
Electrical Performance	800 - 1600Mbps	1600 – 3200Mbps	

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#### **Product Features**

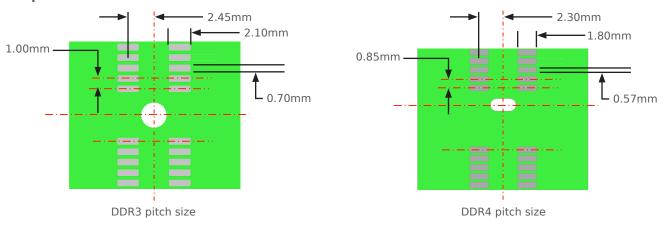
#### **Through Hole Pitch Sizes**

DDR4 DIMM Sockets, Halogen-free

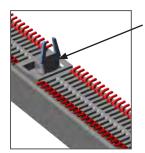


DDR4 uses a smaller pitch and via hole diameter than DDR3 Through hole versions

#### **SMT Footprint**



#### **Socket Housing**

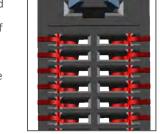


Underside of SMT version DDR4 DIMM Socket showing housing and soldertail design



Recessed soldertail terminals of the SMT DDR4 DIMM Socket

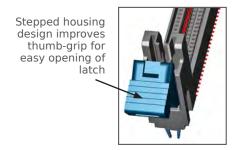
Recessed terminal design of the socket reduces exposure of terminal from physical damage



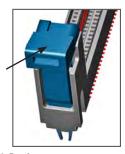
Soldertails of the SMT DDR4 DIMM socket are flush with the connector edge (width) on both sides

Flush soldertail design minimizes accidental damage to terminal due to bending

#### **Ergonomically designed latches**



Though compact, each latch delivers an actuation force of up to 4.50 kgf



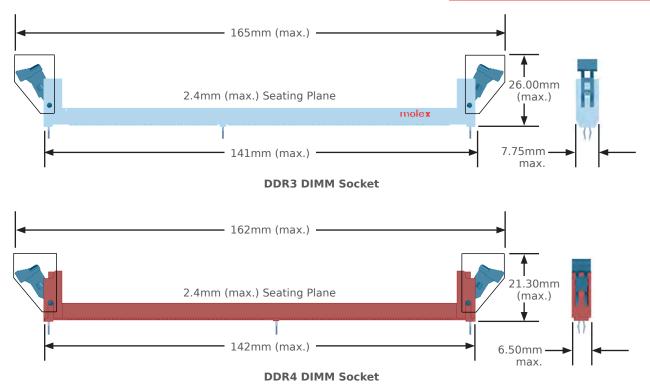
Ergonomically designed latches of the DDR4 DIMM Sockets in open (left) and closed (right) positions



#### **Product Features**

**Differences in socket dimensions** 

DDR4 DIMM Sockets, Halogen-free

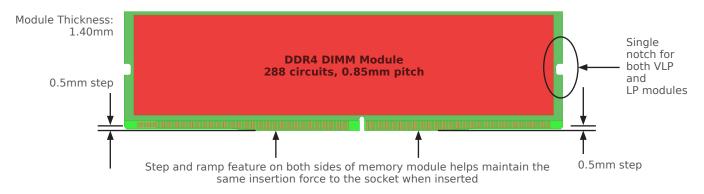


DDR4 has a narrower connector width and mounted height than DDR3 versions

#### **Product Features**

Differences in DDR3 and DDR4 memory modules





Differences between DDR3 and DDR4 Memory Modules



#### **Ordering Information**

DDR4 DIMM Sockets, Halogen-free

#### **Through Hole Versions**

Order No.	Housing Color	Latch Color	Recommended PCB Thickness (mm)	Plating	Product Specification
78726-1002			1.57		
78726-1003	Black Black	Black	2.36		
78726-1026			3.00		
78726-1040		1.57			
78726-1004		Off-white	1.57		
78726-1005		OII-WIIILE	2.36		
78726-1027			3.00		
78726-1006			1.57	6 0.76μm (30μ") Gold (Au) on contact;	
78726-1007		Black	2.36		
78726-1028	Off-white		3.00		
78726-1008	OII-WIILE	wnite	1.57		PS-78726-001
78726-1009	]	Off-white	2.36	2127 p (Sop. 7 mener (m. 7 ander piace	
78726-1029			3.00		
78726-1010			1.57		
78726-1011		Blue	2.36		
78726-1030	]		3.00		
78726-1044	Blue Off-white		1.57		
78726-1022		Offl-:	1.57		
78726-1023		Off-white	2.36		
78726-1031			3.00		
78726-1045			1.57	1.57	
78726-1012		Black 1.57 2.36			
78726-1013			2.36		PS-78726-002
78726-1032	Black		3.00		
78726-1014		Off-white	1.57		
78726-1015			2.36		
78726-1033			3.00		
78726-1016	Off-white Off-white		1.57	0.38μm (15μ") Gold (Au) on contact; 2.54μm (100μ") Tin (Sn) on soldertails;	
78726-1017		Black	2.36		
78726-1034			3.00		
78726-1048		1.57	1.27µm (50µ") Nickel (Ni) underplate	P3-78720-002	
78726-1018		Off-white	1.57		
78726-1019		Oπ-wnite	2.36		
78726-1035			3.00		
78726-1020	Blue	Blue	1.57		
78726-1021			2.36		
78726-1036			3.00		
78726-1024	Blue		1.57		
78726-1025		Off-white	2.36		
78726-1037			3.00		

#### **SMT Versions**

Order No.	Housing Color	Latch Color	Plating	Product Specification
78730-1002	Black	Black		
78730-1003	DIACK	Off-white	0.76μm (30μ") Gold (Au) on contact;	DC 70720 001
78730-1004	Off white	Black 1.27µm (50µ") Nickel (Ni) underplate	2.54µm (100µ") Tin (Sn) on soldertails; 1.27µm (50µ") Nickel (Ni) underplate	PS-78730-001
78730-1005	Off-white	Off-white		

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#### **Applications**

- Data/Computing

  High-end computing

  Personal computers

Telecommunications/Networking

- Infrastructure
- Networking



Servers



Networking systems

**DDR4 DIMM** Sockets, Halogen-free



Data centers

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